

# Per-Erik Tegehall

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/6489828/publications.pdf>

Version: 2024-02-01

17  
papers

257  
citations

1163117

8  
h-index

1372567

10  
g-index

17  
all docs

17  
docs citations

17  
times ranked

190  
citing authors

| #  | ARTICLE   | IF  | CITATIONS |
|----|---|-----|-----------|
| 1  | Nucleation and formation of zinc phosphate conversion coating on cold-rolled steel. <i>Corrosion Science</i> , 1991, 32, 635-652.   | 6.6 | 57        |
| 2  | The mechanism of chemical activation with titanium phosphate colloids in the formation of zinc phosphate conversion coatings. <i>Colloids and Surfaces</i> , 1990, 49, 373-383.   | 0.9 | 37        |
| 3  | Colloidal titanium phosphate, the chemical activator in surface conditioning before zinc phosphating. <i>Colloids and Surfaces</i> , 1989, 42, 155-164.   | 0.9 | 27        |
| 4  | Effect of PCB cracks on thermal cycling reliability of passive microelectronic components with single-grained solder joints. <i>Microelectronics Reliability</i> , 2019, 93, 61-71.   | 1.7 | 23        |
| 5  | Synthesis of Crystalline Titanium(IV) Phosphates by Direct Precipitation from Ti(III) Solutions and Ion Exchange Properties of Some of the Prepared Phases.. <i>Acta Chemica Scandinavica</i> , 1986, 40a, 507-514.   | 0.7 | 22        |
| 6  | Thermal Cycling Aging Effect on the Shear Strength, Microstructure, Intermetallic Compounds (IMC) and Crack Initiation and Propagation of Reflow Soldered Sn-3.8Ag-0.7Cu and Wave Soldered Sn-3.5Ag Ceramic Chip Components. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2008, 31, 331-344. | 1.3 | 21        |
| 7  | Reliability of Microtechnology. , 2011, , .   |     | 19        |
| 8  | Impact of laminate cracks under solder pads on the fatigue lives of ball grid array solder joints. <i>Microelectronics Reliability</i> , 2015, 55, 2354-2370.   | 1.7 | 13        |
| 9  | Ion Exchange on alpha-Titanium Phosphate and Formation of New Crystalline Phases by Hydrolysis of the Ion-Exchanged Phases.. <i>Acta Chemica Scandinavica</i> , 1989, 43, 322-330.  | 0.7 | 13        |
| 10 | Simulations of the impact of single-grained lead-free solder joints on the reliability of ball Grid Array components. , 2017, , .   |     | 8         |
| 11 | The Stress State of BGA Solder Joints Influenced by the Grain Orientations of Neighboring Joints. , 2018, , .   |     | 5         |
| 12 | Printed circuit boards for lead-free soldering: materials and failure mechanisms. <i>Circuit World</i> , 2007, 33, 10-16.   | 0.9 | 4         |
| 13 | On the formation and propagation of laminate cracks and their influence on the fatigue lives of solder joints. , 2018, , .  |     | 3         |
| 14 | Transgranular Crack Propagation in Thermal Cycling of SnAgCu Solder Joints. , 2019, , .   |     | 2         |
| 15 | Evolution of Intermetallic Compounds in PBGA Sn-Ag-Cu Solder Joints during Thermal Cycling Testing. , 2006, , .   |     | 1         |
| 16 | Effect of different temperature cycling profiles on the crack initiation and propagation of Sn-3.5Ag wave soldered solder joints. <i>Microelectronics Reliability</i> , 2007, 47, 266-272.  | 1.7 | 1         |
| 17 | Thermo-mechanical simulations and measurements on high temperature interconnections. , 2011, , .  |     | 1         |